

PCN Number:	20240116005.1		PCN Date:	January 16, 2024	
Title:	Qualification of RFAB as an additional Fab site option, Die Revision, and BOM Option for select devices				
Customer Contact:	Change Management Team		Dept:	Quality Services	
Proposed 1st Ship Date:	Apr 16, 2024		Sample requests accepted until:	Feb 16, 2024*	
*Sample requests received after February 16, 2024 will not be supported.					
Change Type:					
<input type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab option in addition to a BOM option for the devices listed below.					
Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
DL-LIN	LINCMOS	150 mm	RFAB	LBC9	300 mm
The die was also changed as a result of the process change.					
Additional BOM items are as follows:					
	Current	Additional			
Bond wire composition, diameter	Cu, 0.96 mil	Cu, 0.8 mil			
Qual details are provided in the Qual Data Section.					
Reason for Change:					
These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Impact on Environmental Ratings					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.					
RoHS	REACH	Green Status	IEC 62474		
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change		
Changes to product identification resulting from this PCN:					
Fab Site Information:					
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
DL-LIN	DLN	USA	Dallas		
RFAB	RFB	USA	Richardson		
Die Rev:					
Current		New			
Die Rev [2P]	Die Rev [2P]				
B	B				

Sample product shipping label (not actual product label):

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2Q:
 MSL 2 / 260C/1 YEAR SEAL DT
 MSL 1 / 235C/UNLIM 03/29/04
 OPT:
 ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0000017
 (20L) CSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

TLC339CPWR	TLC339IPWR	TLC3704CPWR	TLC3704IPWR
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For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TLC3704IPWR	Qual Device: TLC339IPWR	QBS Reference: OPA4991QPWRQ1	QBS Reference: TLV1824DR	QBS Reference: TLV1814DR
HAST	A2	Biased HAST	110C/85%RH	96 Hours	-	-	3/231/0	-	-
UHA	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	1/3/0	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-

- QBS: Qual By Similarity
- Qual Device TLC339IPWR is qualified at MSL1 260C
- Qual Device TLC3704IPWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2312-005

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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